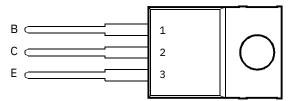
- Designed for Complementary Use with the BD241 Series
- 30 W at 25°C Case Temperature
- 2 A Continuous Collector Current
- 4 A Peak Collector Current
- Customer-Specified Selections Available

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	R/	ATING	SYMBOL VALUE	E UNIT
BD240 -55 BD240A -70 BD240B CER -90 BD240C -115	Collector-emitter voltage (RBE = 100Ω)VV			
BD240 -45 BD240A -60	Collector-emitter voltage (IC = -30 mA)VV			
BD240B CEO -80 BD240C -100	Collector-enlitter voltage (IC = -30 IIIA) VV			
	Emitter-base voltageVEBO-5V			
	Continuous collector currentIC-2A			
	Peak collector current (see Note 1)ICM-4A			
	Continuous base currentIB-0.6A			
	Continuous device dissipation at (or below) 25°C case temperature (see Note 2)Ptot30	0W		
	Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)Ptot	t2W		
	Unclamped inductive load energy (see Note 4)½LIC232m.			
	Operating junction temperature rangeTj-65 to +150°C			
	Storage temperature rangeTstg-65 to +150°C			
	Lead temperature 3.2 mm from case for 10 secondsTL250°C			

NOTES:1. This value applies for tp \leq 0.3 ms, duty cycle \leq 10%.

- 2.Derate linearly to 150°C case temperature at the rate of 0.24 W/°C.
- 3.Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, IB(on) = -0.4 A, RBE = 100 Ω , VBE(off) = 0, RS = 0.1 Ω , VCC = -20 V.



BD240, BD240A, BD240B, BD240C PNP SILICON POWER TRANSISTORS

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electrical characteristics at 25°C case temperature

	PARAMETERTEST CONDITIONSMINTYP	MAX	UNIT
BD240 -45			
Collector-emitter BD240A -60 V(BR)CEOI = -3 breakdown voltageC0 mAIB = 0BD240B-80 (see Note 5) BD240C -100			٧
	VCE= -55 VVBE=0BD24	0-0.2	
Collector-emitterV= ICE-70 VVBE=0BD240A-0.2CES	cut-off currentVCE= -90 VVBE=0BD240I VCE=-115 VVBE=0BD240I		mA
ICEBCEO	Collector cut-offV= -30 VI=0BD240/240, currentVCE= -60 VIB=0BD240B/240		mA
Emitter cut-off			μΑ
LEBPENTE E B CH=0-1			
Forward currentV =			
hCE -4 VIC=-0.2A40FE(see Notes 5 and 6) transfer ratioVCE = -4 VIC= -1A15			
Collector-emitter			V
saturation voltageBC	VCE(sat)I = -0.2 AI= -14(see Notes 5 and 6	5)-0.7	
Base-emitter			V
voltage CE C	VBEV = -4 VI= -1 A(see Notes 5 and 6	5)-1.3	
Small signal forward			
hfeV = current transfer ratioCE -10 VIC=-0.2Af = 1 kHz20			
Small signal forward			
thre ty tanger 1904 and 2015			

duffent transfer ratio EEE = 1 MHz3

NOTES:5.These parameters must be measured using pulse techniques, tp = 300 μ s, duty cycle \leq 2%.

6. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

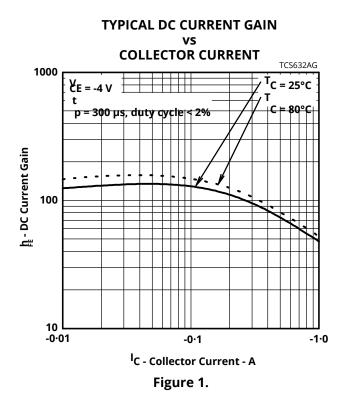
PARAMETER	MIN	TYP	MA	UNI
R _{IC} Junction to case thermal resistance			Х	Т
9 JA Junction to free air thermal resistance			4.17	°C/W
– R			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

PARAMETERTEST CONDITIONS †	MIN	TYP	MAX	UNIT	l
tonTurn-on timeIC = -200 mAIB(on) = -20 mAIB(off) = 20 mA		0.2		μs	
toffTurn-off timeVBE(off) = 3.4 VRL = 150 Ω tp = 20 μ s, dc \leq	≦ 2%	0.4		μs	

Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

TYPICAL CHARACTERISTICS



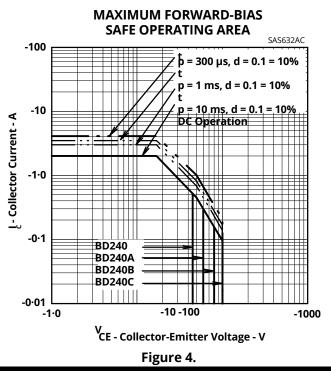
COLLECTOR-EMITTER SATURATION VOLTAGE VS BASE CURRENT TCS632AE -10 -1-0 -

Figure 2.

BASE-EMITTER VOLTAGE COLLECTOR CURRENT TCS632AF -1.0 $V_{CE} = -4 V$ C = 25°C -0.9 V. - Base-Emitter Voltage - V -0.8 -0.7 -0·6 -0·5 ∟ 0·01--0·1 -1.0 IC - Collector Current - A Figure 3.

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MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION VS CASE TEMPERATURE TIS631AB TIS631AB TIS631AB TIS631AB TIS631AB TIS631AB TIS631AB TIS631AB

Figure 5.

PRODUCT INFORMATION

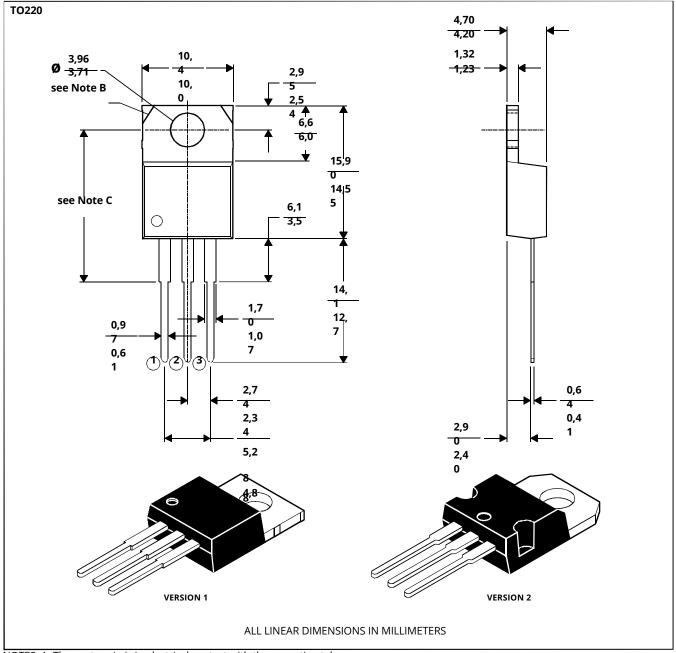
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version.

Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE



BD240, BD240A, BD240B, BD240C PNP SILICON POWER TRANSISTORS

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